Notice Date:

06/03/2004

Product Category:

A/D Converters; Binary and BCD A to D Converters; Display A to D Converters; Dual Slope A to D Converters; dsPIC; Serial Communication; Core 14; Core 16; PIC16xxx; PIC18xxx

Notification Subject:

Change #502 - D/A Change to 3290

Notification Body:

Devices:
DSPIC30F2010
MCP23016
PIC14000
PIC16C55, PIC16FR55
PIC16C557, PIC16LC557
PIC16C55A, PIC16LC55A
PIC16C57, PIC16FR57
PIC16C57C, PIC16LC57C
PIC16C62A, PIC16FR62A, PIC16LC62A, PIC16LFR62A
PIC16C62B, PIC16LC62B
PIC16C63, PIC16FR63, PIC16LC63, PIC16LFR63
PIC16C63A, PIC16LC63A
PIC16C641
PIC16C642, PIC16LC642
PIC16C66, PIC16FR66, PIC16LC66, PIC16LFR66
PIC16C72, PIC16FR72, PIC16LC72, PIC16LFR72
PIC16C72A, PIC16LC72A
PIC16C73A, PIC16FR73A, PIC16LC73A, PIC16LFR73A
PIC16C73B, PIC16LC73B
PIC16C745
PIC16C76, PIC16FR76, PIC16LC76, PIC16LFR76
PIC16C773, PIC16LC773
PIC16CR57B
PIC16CR57C, PIC16LCR57C

PIC16CR63
PIC16CR72
PIC16F57
PIC16F648A
PIC16F716
PIC16F72, PIC16LF72
PIC16F73, PIC16LF73
PIC16F737, PIC16LF737
PIC16F76, PIC16LF76
PIC16F767, PIC16LF767
PIC16F870, PIC16LF870
PIC16F872, PIC16LF872
PIC16F873, PIC16LF873
PIC16F873A, PIC16LF873A
PIC16F876, PIC16LF876
PIC16F876A, PIC16LF876A
PIC18C242, PIC18LC242
PIC18C252, PIC18LC252
PIC18F2220, PIC18LF2220
PIC18F2320, PIC18LF2320
PIC18F2331, PIC18LF2331
PIC18F242, PIC18LF242
PIC18F2431, PIC18LF2431
PIC18F2439, PIC18LF2439
PIC18F248, PIC18LF248
PIC18F252, PIC18LF252
PIC18F2539, PIC18LF2539
PIC18F258, PIC18LF258
PIC18F2585, PIC18LF2585
PIC18F2586, PIC18LF2586
PIC18F2620, PIC18LF2620
PIC18F2620, PIC18LF2620
PIC18F2680, PIC18LF2680
PIC18F2681, PIC18LF2681
TC514
TC530

Description of Change:
Qualification of Ablebond 3280 low stress die attach epoxy in 28L SPDIP package assembly at MTAI.

Impacts to Data Sheet:
None

Reason for Change:
Materials/process improvement

Markings to Distinguish Revised From Unrevised Devices: (e.g.: Date Code, Device Marking, Ship ContainerMarking)
CC0, Date Code, Traceability Code